

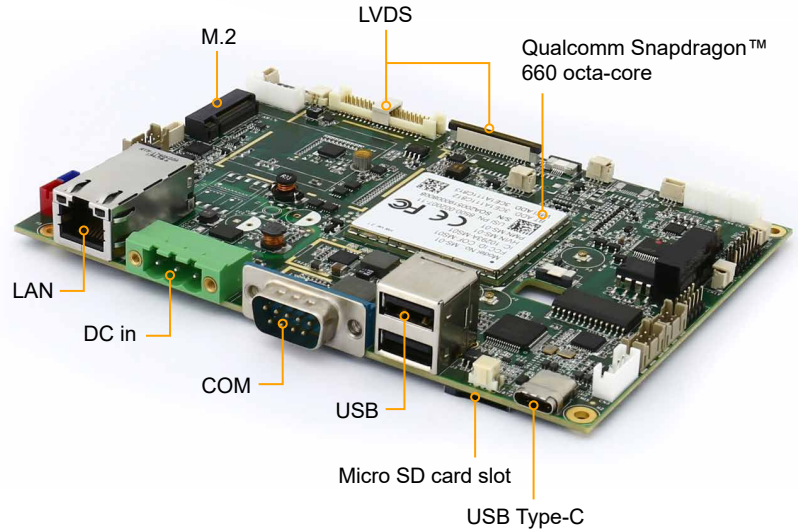
IQ30 3.5" SBC

W/DC 12V Input

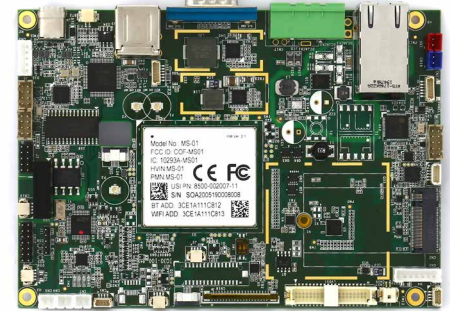
Qualcomm Snapdragon™ 660 octa-core, 3.5" Motherboard

Features

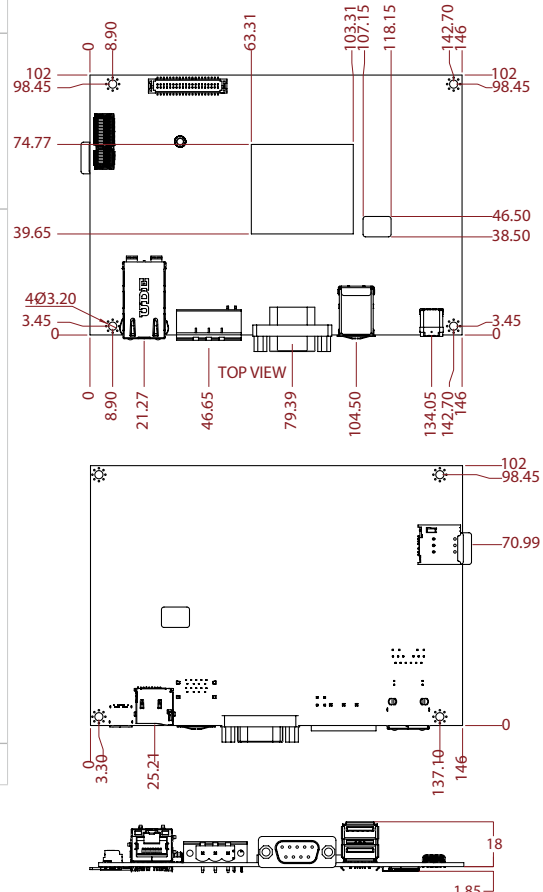
- 3.5" Form Factor (146 mm x 102 mm)
- Qualcomm Snapdragon™ 660 octa-core, 2.2 GHz CPU
- Integrated LVDS, eDP (Optional)
- 3GB LPDDR4 (Optional 4GB), 32GB eMMC
- Rear IO Supports 1 x COM, 2 x USB 2.0, 1 x USB Type C, 1 x LAN, 1 x Micro SD card slot



Top View



Board Dimension(mm)



Specification		
System Specification	Processor	Qualcomm Snapdragon™ 660 octa-core, 2.2 GHz CPU
	Memory	3GB LPDDR4 (Optional 4GB)
	Storage	32GB MLC
	Operating system	Android 9.0
Display Specification	Interface	1 x EDP (MIPI to EDP) 1 x LVDS (MIPI to LVDS)
RF	WLAN	Wi-Fi a/b/g/n/ac
	BT	BT 5
Audio	Codec	PM660L
	Audio Interface	Speaker, Line Out, MIC
I/O Connectors	Rear I/O	2 x USB 2.0 Type A 1 x Terminal Block(Optional for 12V DC Jack) 1 x Micro SD Card Slot 1 x Micro SIM Card Slot 1 x USB Type-C 1 x LAN(USB to LAN AX8817A)(Optional for PoE at/af) 1 x RS232/422/485(Full COM)
	Internal I/O	2 x Light BAR / 1x4-pin with UART 2 x Backlight wafer(5V/3.3V) 1 x LVDS (DF13/FPC) 1 x EDP (15 Pin Wafer) 1 x SW1 (SW Burning Switch) 2 x DMIC (4 Pin Wafer/Per) 2 x USB 2.0 Touch (FFC Connector) 1 x GPIO for 5 key OSD (6 Pin Wafer) 1 x GPIO For Membrane (2x5 Wafer) 1 x Analog MIC (2 Pin Wafer) 2 x Speaker (L/R, 2 Pin Wafer) 1 x 14 Pin DIDO (6 DI, 6 DO, GND, 5V) 1 x 4 Pin Wafer CANBus With Isolation (CANH, CANL, 5V) 1 x 10 Pin COM Port (Full COM RS232, 5V) 3 x USB 2.0 (2x4 Wafer/per) 1 x RTC Battery 1 x Debug Port (6 Pin Wafer) 1 x 5V output (2 Pin Wafer) 1 x 3.3V output (2 Pin Wafer) 1 x UART (TX, RX, 3.3V, GND) 1 x M.2 (PCIe Signal With USB) 1 x I2C 3 x ANT (Wi-Fi, BT, NFC)
Power Requirements	Power Input	12V DC input